Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3064	(gold au) adj bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:51
L2	5027230	gold au	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:51
L3	668820	nickle nickel ni	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:51
L4	1209554	copper cu	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:51
L5	635	2 adj 3 adj 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:52
L6	7142	438/613-617.ccls. 257/737,738.ccls. 228/180.22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:53
L7	46	5 and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:53
L8	762440	@ad>"20030320" @rlad>"20030320" @pt1d>"20030320"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:53
L9	45	7 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:54
L10	1830	4 adj solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:54
L11	152	10 and 6 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:54
L12	2	11 and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:04
L13	87938	bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:04
L14	18	13 with 5 not (11 6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:12
L15	1783	257/e23.021	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:13
L16	953	257/e23.068	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR- -	ON	2004/12/11 16:13
L17	1529	257/e23.069	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:13
L18	1830	257/e21.508	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:14

L19	3271	17 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:14
L20	8	19 and 5 not (6 7 9 14)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:16
L21	57	10 and 19 not (6 7 9 14 20)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:21
L22	152	2 adj 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:21
L23	3	22 with 3 with 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:35
L24	4	("2002/0056906").URPN.	USPAT	OR	ON	2004/12/11 16:32
L25	77	1 with 3 with 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:36
L26	55	25 not 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:49
L27	3	"06056661"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:50
L28	2	"07240420"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:55
L29	1	1995-354177.NRAN.	DERWENT	OR	ON	2004/12/11 16:50
L30	1	2004-697794.NRAN.	DERWENT	OR	ON	2004/12/11 16:52
L31	37416	2 with 3 with 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:56
L32	22492	4 with solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:56
L33	3609	31 and 32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:56
L35	660	31 with bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:58
L37	734	33 and (6 19)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:59
L38	688	31 and 32 and (6 19) not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:59
L39	172	38 not (6 7 9 14 20 21)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 17:11
L41	169	438/614.ccls. and 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 17:12
L42	157	41 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 17:12

L43	7	(US-20030234276-$ or US-20030155638-$ or US-20020056906-$ or US-20020061641-$).did. or (US-4078980-$ or US-6809020-$ or US-4042954-$).did.	US-PGPUB; USPAT	OR	ON	2004/12/11 18:09
L44	1	semiconductorl adj flipl adj chipl adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 18:59
L45	761	semiconductorl adj chipl adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:04
L46	3326	(topl upperl) adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:04
L48	2016916	"438"/$.ccls. "257"/$.ccls. semiconductor integrated adj circuit ic 228/180.22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:05
L49	350041	dice$ dicing scrib$ saw$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:06
L50	49	46 with 49	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:06
L52	47	50 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:08
L53	762	46 and 49	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:09
L54	94	flipl adj chip and 53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:09
L55	84	54 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:10
L56	2	("5,952,725").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 19:13
L57	755	438/113.ccls. not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:13
L58	150	flipl adj chip and 57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:21
L59	4788	cu adj sn	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:22
L60	4	5 with 59	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 20:30
L61	6178	4 with (tin sn) with wt$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 20:32
L62	11	438/614 and 61 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 20:33
L63	11	(US-20030234276-$ or US-20030155638-$ or US-20020056906-$ or US-20020061641-$).did. or (US-4078980-$ or US-6809020-$ or US-4042954-$ or US-6762506-$ or US-6638847-$ or US-6334570-$ or US-6325279-$).did.	US-PGPUB; USPAT	OR	ON	2004/12/11 21:29

L64	12	electroplat$ with electroless with equivalent$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:30
L65	12	64 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:32
L66	164	electroplat$ with electroless$ with bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:33
L67	152	66 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:33

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solder[2,verb]

Main Entry: **¹sol·der** 🔊
Pronunciation: 'sä-d&r, 'so-, *British also* 'säl-d&r, 'sol-
Function: *noun*
Etymology: Middle English *soudure,* from Middle French, from *souder* to solder, from Latin *solidare* to make solid, from *solidus* solid
1 : a metal or metallic alloy used when melted to join metallic surfaces; *especially* : an alloy of lead and tin so used
2 : something that unites

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